



Product and Packaging Protection to Combat Counterfeit Electronic Components - A Best Practice Workshop...

BIS Conference Centre, 1 Victoria Street, London SW1 - 9th March 2010

Why this Workshop?

Counterfeiting of electronic products and components poses increased threats, not only in economic terms, but also to the critical infrastructure of the industry. These components provide much of the enabling technology at the core of both industrial and consumer products. The effects of malfunctioning counterfeit components can compromise performance, safety and may result in substantial additional costs for the brand owner.

There are several initiatives under development to share intelligence and best practice to aid the detection of counterfeit components already in the electronic components supply network. However, the level of concern within component manufacturer, distribution and the OEM community is such that it is becoming imperative to explore the options for using technology that is designed to assist with authenticating products and components within the supply network. That technology is available now and component manufacturers and suppliers who successfully integrate counter measures into their devices and packaging may gain a competitive advantage by offering components that can be readily authenticated further along the supply network by customers and enforcement authorities.

Following a number of successful seminars aimed at raising awareness of the issue of counterfeit electronic components, the UK Electronics Alliance and the Electronic Component Supply Network, together with the Product & Image Security Foundation, the forum for security labelling, packaging and marking suppliers, are holding a further seminar to discuss potential solutions to the problems of identifying and removing counterfeit components from the supply chain.

What's included?

The seminar, scheduled to run from 10.00am to 3.30pm with breaks for refreshments and lunch, will provide:

- A look at the most suitable solutions and traceability systems for electronic component identification and how they can be supported by legal and official frameworks
- Information on how track and trace systems should complement each other and provide protection to protect the product and the packaging
- An overview of current technology including holograms and optically based security devices; track and trace systems; marking systems including SMS messaging and internet codes; Molecular Computational Identification Devices (MCID), tags and taggants; and surface feature identification and random marking

Participants will also be able to receive pertinent diagnostic advice and remedies to their specific problems where practical.



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Who should attend?

Electronic component manufacturers, distributors and OEM's who are considering introducing or improving their brand and packaging protection systems will find this seminar particularly useful as will users of electronic components who wish to be appraised of the latest technology to aid the detection of counterfeit electronic components.

Presentations will include:

Introduction and assessment of authentication and how different approaches may be necessary to satisfy the need to apply effective anti-counterfeiting solutions - *Jeremy Plimmer, Product & Image Security Foundation*

Mass serialisation and the importance of introducing a 'holistic' approach to brand protection - *Richard Burhouse, Payne Security*

Surface feature authentication and how specific product 'biometrics' can be utilised as authentication features in brand protection programs - *Mark McGlade, Ingenia Technology*

The addition of forensic markers to products and packaging assists brand owner protection initiatives, especially if such markers can be added to plastics and coatings as part of the manufacturing process - *David Wells, Addmaster*

How microtaggants and other printed security features can be used to identify counterfeit electronics components - *Angelina Rayak, 3S Simons Security Systems*

Laser activated security ink activation for product marking and other security ink technologies for packaging and labelling - *Trevor Wilson – Xipirt Lasers and Peter Paul, Printcolor*

How to get to the BIS Conference Centre

By London Underground

Both Westminster (Exit 6) on the District, Circle and Jubilee lines, and St James's Park on the District and Circle lines, are 5 minutes walk away.

By main line train

London's mainline stations at Waterloo, Victoria and Charing Cross are approximately 15 minutes walk away.

For a location map, please go to

<http://www.streetmap.co.uk/map.srf?x=529833&y=179415&z=0&sv=SW1H+0ET&st=2&pc=SW1H+0ET&mapp=map.srf&searchp=ids.srf>

Fees and terms

£65 plus VAT per delegate (£74.75 incl. VAT if booked by 31st December or £76.38 if booked from 1st January) or £45 plus VAT per delegate (£51.75 incl. VAT if booked by 31st December or £52.88 if booked from 1st January) for members of the COG, Electronic Components Supply Network, Electronics KTN, Electronics Scotland, EY, GAMBICA, Intellect, JEMI, NMI, UK Electronics Alliance or Welsh Electronics Forum.

To book, please go to <http://www.regonline.co.uk/Checkin.asp?EventId=802993> Alternatively, payment may be made by cheque, drawn on a UK clearing bank in sterling and made payable to the UK Electronics Alliance Ltd. Please send your cheque, together with the names of delegates attending, by post to UK Electronics Alliance, The Old Forge, Rectory Lane, Brasted, Kent TN16 1JS

If you have any queries or for the members' discount code, please contact us on ukelectronicalliance@gmail.com